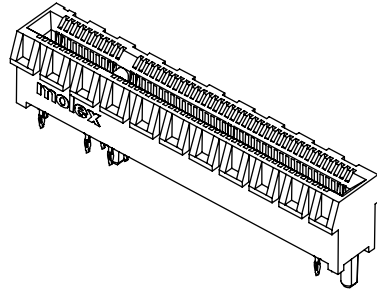


1.00mm (.039") Pitch PCI Express* ExpressModule* (SIOM) Socket

78033
Vertical, Press-Fit



Features and Benefits

- High-temperature thermoplastic housing for lead-free processing
- Complies with PCI-SIG* industry specifications to ensure connectors support all ExpressModule* available in the market
- Key design ensures correct mating of card module to edge card connector
- Press-fit termination allows solderless termination on PCBs with high layer count
- Wider lead-in design to better facilitates blind mating

Reference Information

Product Specification: PS-78028-001
Packaging: Tray
Mates With: 1.57mm (.061") thick ExpressModule
Designed In: Millimeters

Electrical

Voltage: 50V AC (RMS)/DC
Current: 1.1A
Contact Resistance: 30 milliohms max.
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min.

Mechanical

Terminal Retention Force: 2.94N min. per terminal
Mating Force: 1.15N max. per contact pair
Unmating Force: 0.15N min. per contact pair
Durability: 50 cycles

Physical

Housing: Black high-temperature nylon, UL 94V-0
Contact: Copper Alloy
Plating: Contact Area—0.76µm (30µ") Gold
Solder Tail Area—Tin
Underplating: Nickel
Operating Temperature: -55 to +85°C

Circuits	Order No.	PC Tail Length	Recommended PCB Thickness	Lead-free
8 Ports, 98 Circuits	78033-0008	2.54mm (.100")	2.30mm (.090")	Yes
	78033-0018	2.79mm (.109")	2.60mm (.102")	
	78033-0028	3.43mm (.135")	3.20mm (.125")	

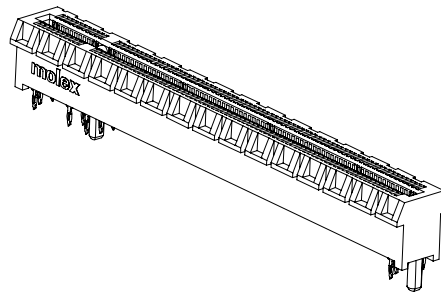
For Tin/Lead option, please contact Molex

*PCI Express, ExpressModule and PCI-SIG are trademarks or registered trademarks of PCI-SIG

www.molex.com/customer.html?seriesNumber=78033

1.00mm (.039") Pitch PCI Express* Edgecard Connector

78028
Vertical, Press-Fit



Features and Benefits

- High-temperature thermoplastic housing for lead-free processing
- Complies with PCI-SIG* industry specifications to ensure connectors support all PCI Express module cards
- Keying design ensures correct mating of card module to edge card connector
- Press-fit termination allows solderless termination on PCBs with high layer count
- Ridge design will be compatible with module cards that require a retention clip for secure retention

Reference Information

Product Specification: PS-78028-001
Packaging: Tray
Mates With: PCI Express* module card
Designed In: Millimeters

Electrical

Voltage: 50V AC (RMS)/DC
Current: 1.1A
Contact Resistance: 30 milliohms max.
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min.

Mechanical

Terminal Retention Force: 2.94N min./terminal
Mating Force: 1.15N max./contact pair
Unmating Force: 0.15N min./contact pair
Durability: 50 cycles

Physical

Housing: Black high-temperature nylon, UL 94V-0
Contact: Copper Alloy
Plating: Contact Area—See table
Solder Tail Area—Tin
Underplating: Nickel
Operating Temperature: -55 to +85°C

Circuits	Order No.	Plating	PC Tail Length	Recommended PCB Thickness	Lead-free
8 Ports, 98 Circuits	78028-0008	0.76µm (30µ") Gold	2.54mm (.100")	2.30mm (.090")	Yes
	78028-0108		2.79mm (.109")	2.60mm (.102")	
	78028-1108		3.43mm (.135")	3.20mm (.125")	
	78028-0018	0.38µm (15µ") Gold	2.54mm (.100")	2.30mm (.090")	
	78028-0118		2.79mm (.109")	2.60mm (.102")	
	78028-1118		3.43mm (.135")	3.20mm (.125")	
16 Ports, 164 Circuits	78028-0016	0.76µm (30µ") Gold	2.54mm (.100")	2.30mm (.090")	
	78028-0116		2.79mm (.109")	2.60mm (.102")	
	78028-1116		3.43mm (.135")	3.20mm (.125")	
	78028-0026	0.38µm (15µ") Gold	2.54mm (.100")	2.30mm (.090")	
	78028-0126		2.79mm (.109")	2.60mm (.102")	
	78028-1126		3.43mm (.135")	3.20mm (.125")	

For Tin/Lead option, please contact Molex

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